



Material Content Data Sheet



Sales Product Name	TLF80511TC			Issued	27. September 2017			
MA#	MA001003488							
Package	PG-TO263-3-1			Weight*	1595.73 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.094	0.07	0.07	686	686
leadframe	inorganic material	phosphorus	7723-14-0	0.091	0.01		57	
	non noble metal	iron	7439-89-6	0.304	0.02		191	
	non noble metal	copper	7440-50-8	304.026	19.05	19.08	190525	190773
	non noble metal	aluminium	7429-90-5	0.213	0.01	0.01	133	133
wire	non noble metal	aluminium	7429-90-5	0.213	0.01	0.01	133	133
encapsulation	organic material	carbon black	1333-86-4	1.461	0.09		916	
	plastics	epoxy resin	-	67.201	4.21		42113	
	inorganic material	silicondioxide	60676-86-0	661.786	41.48	45.78	414722	457751
leadfinish	non noble metal	tin	7440-31-5	9.657	0.61	0.61	6052	6052
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1	
	non noble metal	nickel	7440-02-0	0.228	0.01	0.01	143	144
solder	non noble metal	tin	7440-31-5	0.026	0.00		16	
	noble metal	silver	7440-22-4	0.032	0.00		20	
	non noble metal	lead	7439-92-1	1.229	0.08	0.08	770	806
heatspreader	inorganic material	phosphorus	7723-14-0	0.165	0.01		103	
	non noble metal	iron	7439-89-6	0.548	0.03		344	
	non noble metal	copper	7440-50-8	547.666	34.32	34.36	343208	343655
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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